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April 1st, 2010
Renesas Electronics Corporation

Issued by: Renesas Electronics Corporation (<http://www.renesas.com>)

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Phase-out/Discontinued μ PD720130

USB2.0 to IDE Bridge



The μ PD720130 is designed to perform a bridge between USB 2.0 and ATA/ATAPI. The μ PD720130 complies with the Universal Serial Bus Specification Revision 2.0 full-/high-speed signaling and works up to 480 Mbps. The μ PD720130 is integrated CISC processor, ATA/ATAPI controller, endpoint controller (EPC), serial interface engine (SIE), and USB2.0 transceiver into a single chip. The USB2.0 protocol and class specific protocol (bulk only protocol) are handled by USB2.0 transceiver, SIE, and EPC. And the transport layer is performed by V30MZ CISC processor which is in the μ PD720130. The software to control the μ PD720130 is located in an embedded ROM. In the future, the μ PD720130 will be released to support external Flash Memory / EEPROM™ option to update function by firmware.

Detailed function descriptions are provided in the following user's manual. Be sure to read the manual before designing.

μ PD720130 User's Manual: S16412E

FEATURES

- Compliant with Universal Serial Bus Specification Revision 2.0 (Data Rate 12/480 Mbps)
- Compliant with ATA/ATAPI-6 (LBA48, PIO Mode 0-4, Multi Word DMA Mode 0-2, Ultra DMA Mode 0-4)
- USB2.0 high-speed bus powered device capability
- Certified by USB implementers forum and granted with USB 2.0 high-speed Logo (TID :40320125)
- One USB2.0 high-speed transceiver / receiver with full-speed transceiver / receiver
- USB2.0 High-speed or Full-speed packet protocol sequencer (Serial Interface Engine)
- Automatic chirp assertion and full-/high-speed mode change
- USB Reset, Suspend and Resume signaling detection
- Supports power control functionality for IDE device as CD-ROM and HDD
- Supports set feature (TEST_MODE) functionality
- System Clock is generated by 30 MHz X'tal
- 2.5 V and 3.3 V power supply

ORDERING INFORMATION

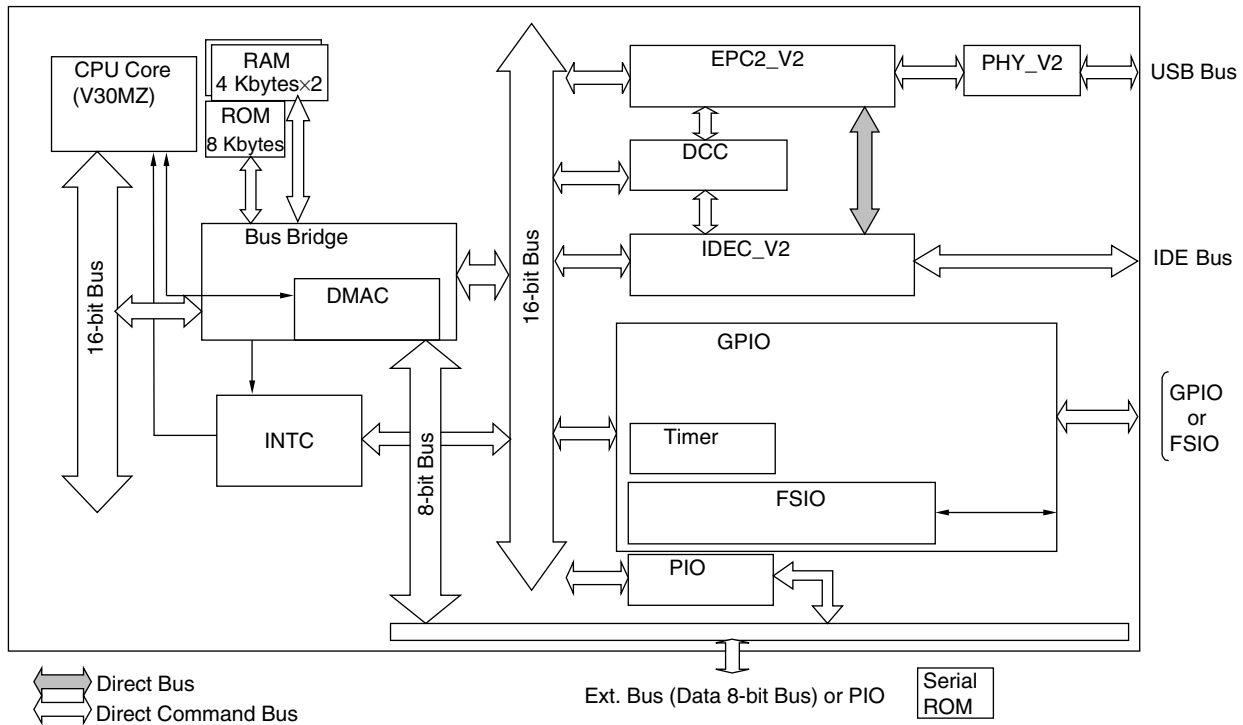
Part Number	Package
μ PD720130GC-9EU	100-pin plastic TQFP (fine pitch) (14 × 14)
μ PD720130GC-9EU-SIN	100-pin plastic TQFP (fine pitch) (14 × 14)
★ μ PD720130GC-9EU-A	100-pin plastic TQFP (fine pitch) (14 × 14)

★ **Remark** μ PD720130GC-9EU-A is a lead-free product.

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Not all devices/types available in every country. Please check with local NEC representative for availability and additional information.

BLOCK DIAGRAM



- V30MZ : CISC CPU core
- RAM : 8-Kbyte work RAM for firmware
- ROM : 8-Kbyte ROM for built-in firmware
- PHY_V2 : USB2.0 transceiver with serial interface engine
- EPC_V2 : Endpoint controller
- IDEC_V2 : IDE controller
- DCC : ATA direct command controller
- Bus Bridge : Internal / external bus controller and DMA controller
- INTC : Interrupt controller (82C59 like)
- GPIO : General purpose 8-bit I/O controller
- PIO : Multipurpose 14-bit I/O controller
- FSIO : Flexible serial I/O

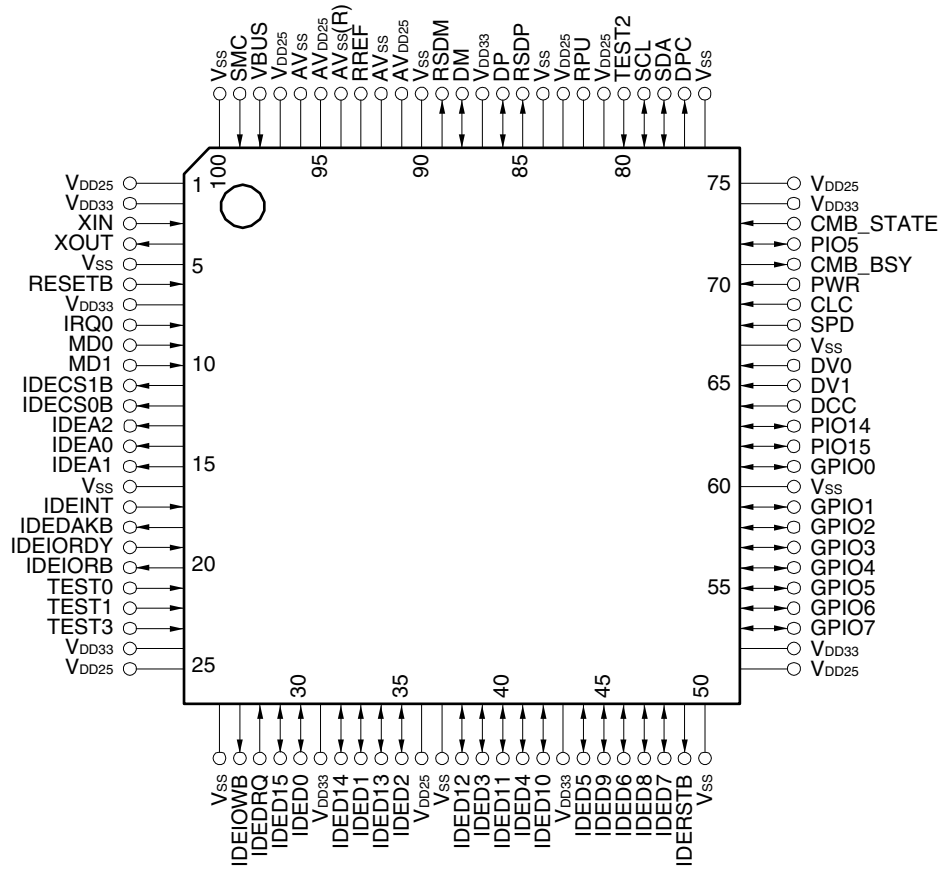
PIN CONFIGURATION (TOP VIEW)

- 100-pin plastic TQFP (fine pitch) (14 × 14)

μPD720130GC-9EU

μPD720130GC-9EU-SIN

★ μPD720130GC-9EU-A



PIN LIST

Pin No.	Pin Name	Pin No.	Pin Name	Pin No.	Pin Name	Pin No.	Pin Name
1	V _{DD25}	26	V _{SS}	51	V _{DD25}	76	V _{SS}
2	V _{DD33}	27	IDEIOWB	52	V _{DD33}	77	DPC
3	XIN	28	IDEDRQ	53	GPIO7	78	SDA
4	XOUT	29	IDED15	54	GPIO6	79	SCL
5	V _{SS}	30	IDED0	55	GPIO5	80	TEST2
6	RESETB	31	V _{DD33}	56	GPIO4	81	V _{DD25}
7	V _{DD33}	32	IDED14	57	GPIO3	82	RPU
8	IRQ0	33	IDED1	58	GPIO2	83	V _{DD25}
9	MD0	34	IDED13	59	GPIO1	84	V _{SS}
10	MD1	35	IDED2	60	V _{SS}	85	RSDP
11	IDECS1B	36	V _{DD25}	61	GPIO0	86	DP
12	IDECS0B	37	V _{SS}	62	PIO15	87	V _{DD33}
13	IDEA2	38	IDED12	63	PIO14	88	DM
14	IDEA0	39	IDED3	64	DCC	89	RSDM
15	IDEA1	40	IDED11	65	DV1	90	V _{SS}
16	V _{SS}	41	IDED4	66	DV0	91	AV _{DD25}
17	IDEINT	42	IDED10	67	V _{SS}	92	AV _{SS}
18	IDEDAKB	43	V _{DD33}	68	SPD	93	RREF
19	IDEIORDY	44	IDED5	69	CLC	94	AV _{SS(R)}
20	IDEIORB	45	IDED9	70	PWR	95	AV _{DD25}
21	TEST0	46	IDED6	71	CMB_BSY	96	AV _{SS}
22	TEST1	47	IDED8	72	PIO5	97	V _{DD25}
23	TEST3	48	IDED7	73	CMB_STATE	98	VBUS
24	V _{DD33}	49	IDERSTB	74	V _{DD33}	99	SMC
25	V _{DD25}	50	V _{SS}	75	V _{DD25}	100	V _{SS}

Remark AV_{SS(R)} should be used to connect RREF through 1 % precision reference resistor of 2.43 kΩ.

1. PIN INFORMATION

(1/2)

Pin Name	I/O	Buffer Type	Active Level	Function
XIN	I	2.5 V Input		System clock input or oscillator In
XOUT	O	2.5 V Output		Oscillator out
RESETB	I	3.3 V Schmitt Input	Low	Asynchronous reset signaling
MD(1:0)	I	3.3 V Input		Function mode setting
IDECS(1:0)B	O (I/O)	5 V tolerant Output	Low	IDE host chip select
IDEA(2:0)	O (I/O)	5 V tolerant Output		IDE address bus
IDEINT	I (I/O)	5 V tolerant Input	High	IDE interrupt request from device to host
IDEDAKB	O (I/O)	5 V tolerant Output	Low	IDE DMA acknowledge
IDEIORDY	I (I/O)	5 V tolerant Input	High	IDE IO channel ready
IDEIORB	O (I/O)	5 V tolerant Output	Low	IDE IO read strobe
IDEIOWB	O (I/O)	5 V tolerant Output	Low	IDE IO write strobe
IDEDRQ	I (I/O)	5 V tolerant Input	High	IDE DMA request from device to host
IDED(15:0)	I/O	5 V tolerant I/O		IDE data bus
IDERSTB	O (I/O)	5 V tolerant Output	Low	IDE reset from host to device
DCC	I (I/O)	3.3 V Input		IDE controller operational mode setting
DV(1:0)	I (I/O)	3.3 V Input		Device select
CLC	I (I/O)	3.3 V Input		System clock setting
PWR	I (I/O)	3.3 V Input		Bus powered /self-powered select
CMB_BSY	O (I/O)	3.3 V Output		Combo IDE bus busy
CMB_STATE	I (I/O)	3.3 V Input		Combo IDE bus state
DPC	O (I/O)	3.3 V Output		Power control signaling for IDE device
SDA	I/O	3.3 V I/O		Serial ROM data signaling
SCL	I/O	3.3 V I/O		Serial ROM clock signaling
VBUS	I	5 V Schmitt Input ^{Note}		VBUS monitoring
DP	I/O	USB high speed D+ I/O		USB's high speed D+ signal
DM	I/O	USB high speed D- I/O		USB's high speed D- signal
RSDP	O	USB full speed D+ Output		USB's full speed D+ signal
RSDM	O	USB full speed D- Output		USB's full speed D- signal
RPU	A	USB Pull-up control		1.5 kΩ pull-up resistor control
RREF	A	Analog		Reference resistor
SPD	I (I/O)	3.3 V Input		NEC private
SMC	I	3.3 V Input		Scan mode control
TEST(3:0)	I	3.3 V Input		Test mode setting

Note VBUS pin may be used to monitor for VBUS line even if V_{DD33}, V_{DD25}, and AV_{DD25} are shut off. System must ensure that the input voltage level for VBUS pin is less than 3.0 V due to the absolute maximum rating is not exceeded.

(2/2)

Pin Name	I/O	Buffer Type	Active Level	Function
GPIO(7:0)	I/O	3.3 V Schmitt I/O		General purpose IO port (for future extension)
PIO(15:14)	I/O	3.3 V I/O		IO port (for future extension)
PIO(5)	I/O	3.3 V Schmitt I/O		IO port (for future extension)
IRQ0	I	3.3 V Schmitt Input	High	External interrupt input (for future extension)
AV _{DD25}				2.5 V V _{DD} for Analog circuit
V _{DD25}				2.5 V V _{DD}
V _{DD33}				3.3 V V _{DD}
AV _{SS}				V _{SS} for Analog circuit
V _{SS}				V _{SS}

- Remarks**
1. "5 V tolerant" means that the buffer is 3.3 V buffer with 5 V tolerant circuit.
 2. The signal marked as "(I/O)" in the above table operates as I/O signals during testing. However, they do not need to be considered in normal use.

2. FUNCTION INFORMATION

USB to IDE system can be realized by the μPD720130, Serial ROM which has USB vender ID, product ID, etc, and power control circuit. The μPD720130 can be selected bus powered mode or self powered mode. If all power consumption for USB to IDE system is less than the specification of bus powered device, it will be possible to realize high-speed capable bus powered system. The μPD720130 has some features for bus powered system. Also, some system may control target IDE device by two IDE controllers. At the time, IDE bus arbitration should be required to each IDE controller. The μPD720130 has a feature of IDE bus arbitration, too.

The setting of IDE controller in the μPD720130 is controlled by data in serial ROM or external pin setting. If there is any inconsistency between data in serial ROM and external pin setting, the data in serial ROM is higher priority than external pin setting.

2.1 Data in Serial ROM

The μPD720130 loads some data such as Vendor ID, Product ID and some additional USB related information, etc from serial ROM when the μPD720130 is initialized. Example of data in serial ROM is as follows. ExPinReset and ExPinSet fields hold data which is related to the external pin setting.

Table 2-1. Data in Serial ROM

Data size	Symbol	Description
1 Word	Flags	Control for descriptor overwrite
1 Byte	ExPinReset	PWR, CLC, DCC, DV[1:0] Reset bit map field
1 Byte	ExPinSet	PWR, CLC, DCC, DV[1:0] Set bit map field
1 Word	idVendor	idVendor field in Device descriptor
1 Word	idProduct	idProduct field in Device descriptor
1 Word	bcdDevice	bcdDevice field in Device descriptor
1 Byte	MaxPower BUS	MaxPower field in Configuration descriptor for Bus powered mode
1 Byte	MaxPower Self	MaxPower field in Configuration descriptor for Self powered mode
1 Byte	bInterfaceClass	bInterfaceClass field in Interface descriptor
1 Byte	bInterfaceSubClass	bInterfaceSubClass field in Interface descriptor
1 Byte	bInterfaceProtocol	bInterfaceProtocol field in Interface descriptor
1 Word	TxMode Reset	IDE transmission type such as Ultra DMA 66 Reset bit map field
1 Word	TxMode Set	IDE transmission type such as Ultra DMA 66 Set bit map field
32 Bytes	ManufactureString	String descriptor for Manufacturer
32 Bytes	ProductString	String descriptor for Product
32 Bytes	SerialString	String descriptor for Device serial number

2.2 External Pin Setting

Usually, serial ROM should be used to keep Vendor ID, Product ID and some additional USB related information. And then, the external pin setting of the μPD720130 is not so important to realize USB to IDE bridge system. The recommended external pin setting is as follows.

Table 2-2. Recommended External Pin Setting

Pin Name	Setting
MD1	1
MD0	0
SCL	Pull Up ^{Note 1}
SDA	Pull Up
DV1	“L” clamp
DV0	“L” clamp
CLC	“L” clamp
PWR	“L” clamp
DCC	Pull Down ^{Note 2}
GPIO(7:0)	“L” clamp
PIO(14:15)	“L” clamp
PIO5	“L” clamp
SPD	“H” clamp
TEST(3:0)	“L” clamp
SMC	“L” clamp
IRQ0	“L” clamp

- Notes**
1. If serial ROM size is more than 2 Kbytes, SCL should be pull down.
 2. If target IDE device is not fixed, it is preferable that DCC pin can switch pull-up or pull-down.

The setting for any other pins such as CMB_BSY, CMB_STATE depends on USB2.0 to IDE Bridge system. For example, if two IDE controllers control one target IDE device and one of two IDE controllers is the μPD720130, CMB_BSY and CMB_STATE are used to handshake between two IDE controller chips. On the other hand, when the μPD720130 is only controller of target IDE device, CMB_BSY should be opened and CMB_STATE should be clamped to “L”.

2.3 Control Bit in Serial ROM or External Pin Setting

The following tables show IDE status and control bit in serial ROM or external pin setting.

Table 2-3. DV1/DV0, CLC, PWR Setting

No.	Device Power	Internal Clock	ATA/ATAPI	Setting in Serial ROM or External Pin			
				PWR	CLC	DV1	DV0
0	Bus Powered	7.5 MHz	No device connected	1	1	1	1
1			ATA	1	1	1	0
2			ATAPI	1	1	0	1
3			Reserved	1	1	0	0
4		60 MHz	No device connected	1	0	1	1
5			ATA	1	0	1	0
6			ATAPI	1	0	0	1
7			Reserved	1	0	0	0
8	Self Powered	60 MHz	No device connected	0	1	1	1
9			Combo (ATA)	0	1	1	0
10			Combo (ATAPI)	0	1	0	1
11			Reserved	0	1	0	0
12			No device connected	0	0	1	1
13			ATA	0	0	1	0
14			ATAPI	0	0	0	1
15			Auto device detect	0	0	0	0

Remark Setting No. 0, 3, 4, 7, 8, 11, and 12 are prohibited to use.

Table 2-4. DV1/DV0, DCC Setting

Condition				DCC Pin Setting	DCC Setting in Serial ROM	Description
DV1	DV0	Mode	Target Device			
1	0	ATA	ATA	0	No setting	Ultra, Multi Word DMA are disabled
				0	Reset	Ultra, Multi Word DMA are disabled
				0	Set	Ultra, Multi Word DMA are enabled.
				1	No setting	Ultra, Multi Word DMA are enabled.
				1	Reset	Ultra, Multi Word DMA are disabled
				1	Set	Ultra, Multi Word DMA are enabled.
0	1	ATAPI	ATAPI	0	No setting	Ultra DMA is disabled
				0	Reset	Ultra DMA is disabled
				0	Set	Ultra, Multi Word DMA are enabled.
				1	No setting	Ultra, Multi Word DMA are enabled.
				1	Reset	Ultra DMA is disabled
				1	Set	Ultra, Multi Word DMA are enabled.
0	0	Auto device detect	ATA	0	No setting	Ultra, Multi Word DMA are disabled
				0	Reset	Ultra, Multi Word DMA are disabled
				0	Set	Ultra, Multi Word DMA are enabled.
				1	No setting	Ultra, Multi Word DMA are enabled.
				1	Reset	Ultra, Multi Word DMA are disabled
				1	Set	Ultra, Multi Word DMA are enabled.
			ATAPI	0	No setting	Ultra DMA is disabled
				0	Reset	Ultra DMA is disabled
				0	Set	Ultra, Multi Word DMA are enabled.
				1	No setting	Ultra, Multi Word DMA are enabled.
				1	Reset	Ultra DMA is disabled
				1	Set	Ultra, Multi Word DMA are enabled.

Remark PIO mode 0-4 are always enabled.

2.4 Combo Mode Function

The μPD720130 can be used to realize that two IDE controller chips control one target IDE device in one system. To realize IDE bus arbitration between two IDE controller chips, the μPD720130 has CMB_BSY and CMB_STATE. Combo mode is enabled when PWR = 0 and CLC = 1.

CMB_BSY and CMB_STATE connect to other IDE controller chip as follows.

Figure 2-1. CMB_BSY and CMB_STATE Connection between Two IDE Controller Chips

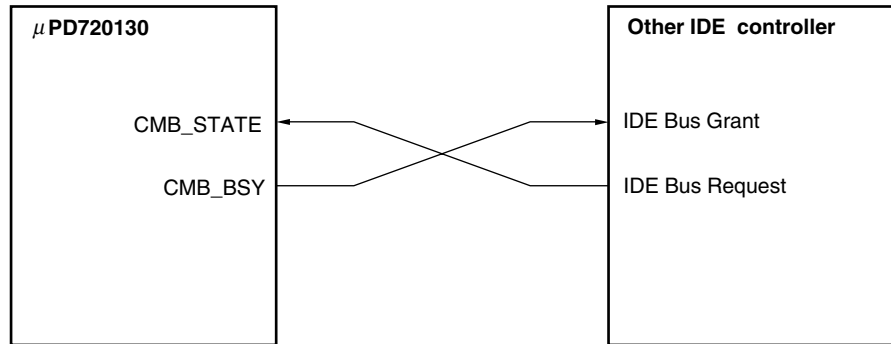
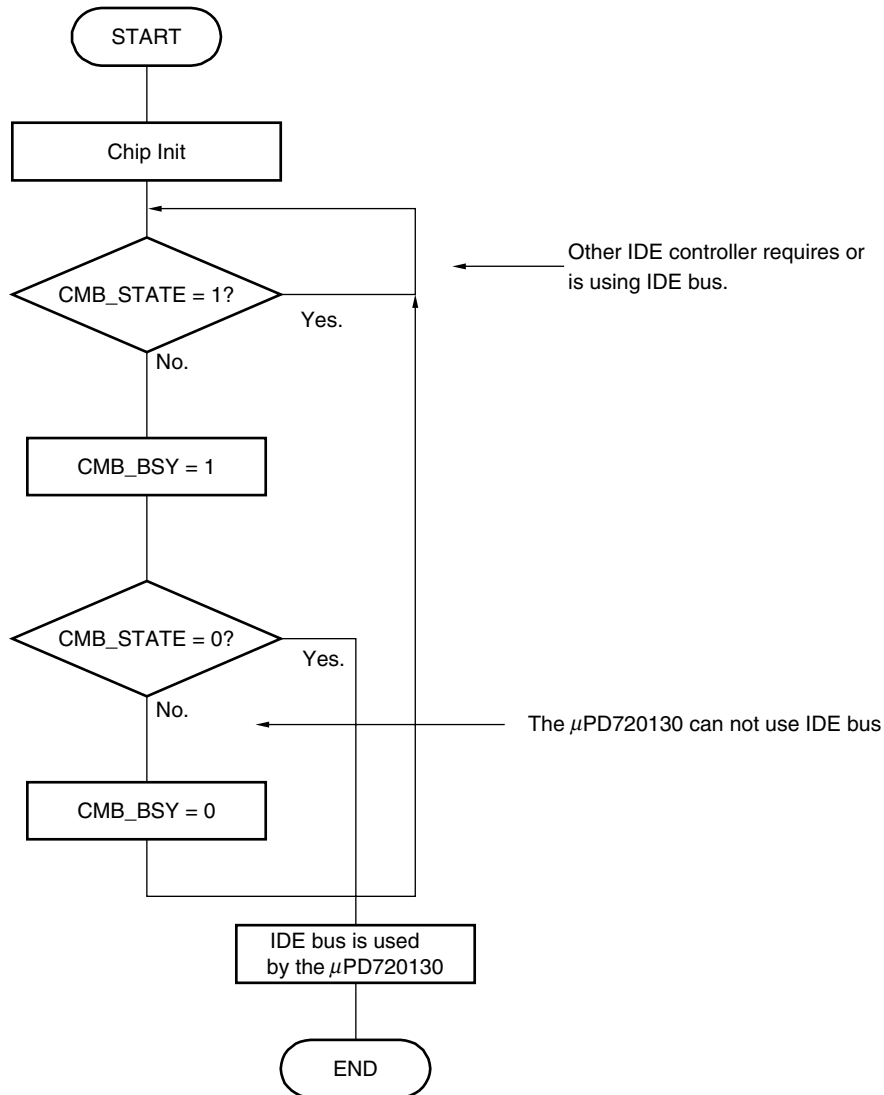


Table 2-5. Description of CMB_BSY and CMB_STATE

Pin Name	Direction	Value	Description
CMB_STATE	IN	0	Other IDE controller does not require or does not use IDE bus.
		1	Other IDE controller requires or is using IDE bus.
CMB_BSY	OUT	0	The μPD720130 does not require or does not use IDE bus.
		1	The μPD720130 requires or is using IDE bus.

The IDE bus arbitration will be done by following sequence. The μ PD720130 will confirm whether other IDE controller requires or is using IDE bus or not. If other IDE controller does not require or does not use IDE bus, the μ PD720130 will use IDE bus.

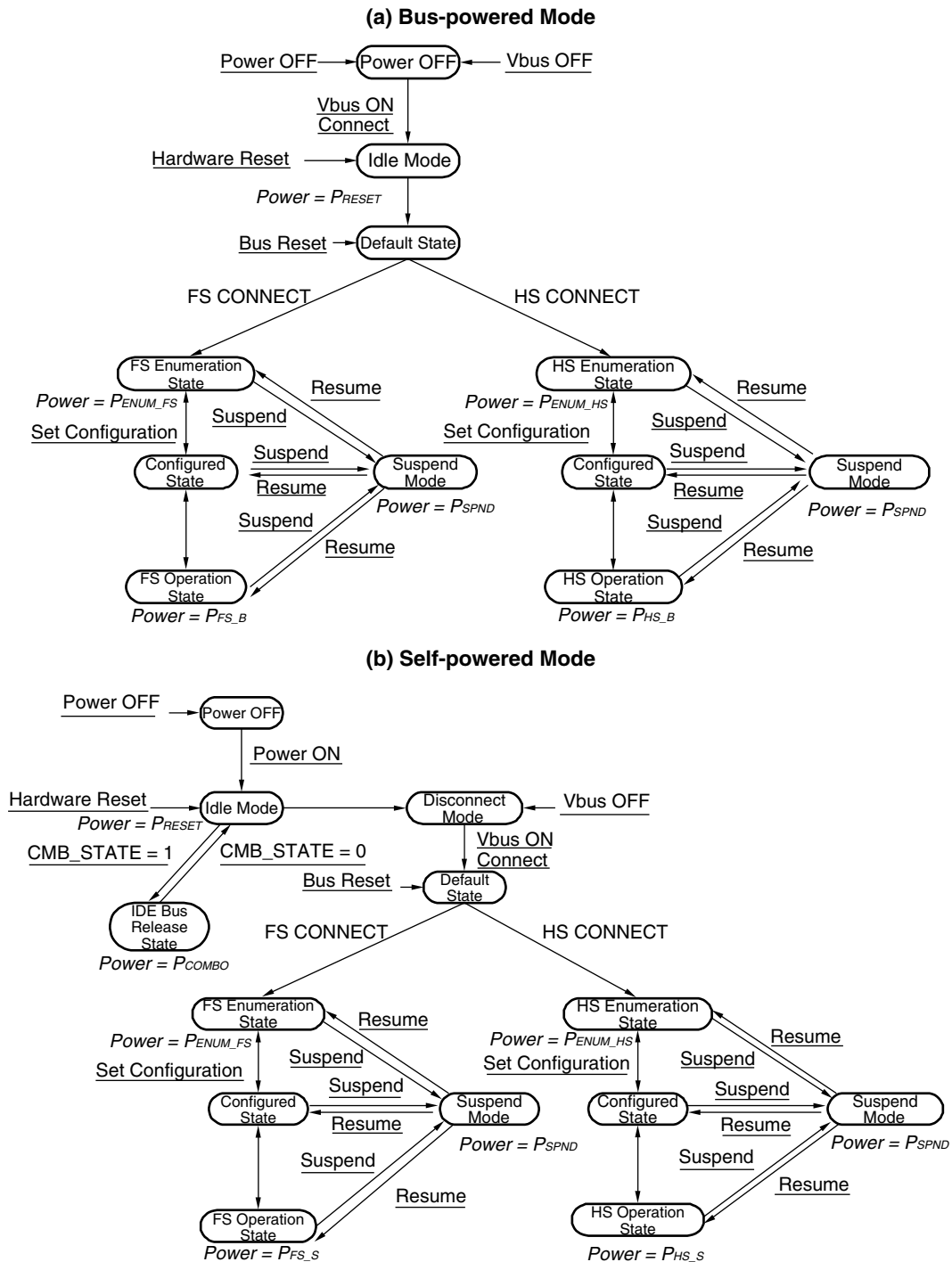
Figure 2-2. IDE Bus Arbitration Sequence



2.5 Power Control

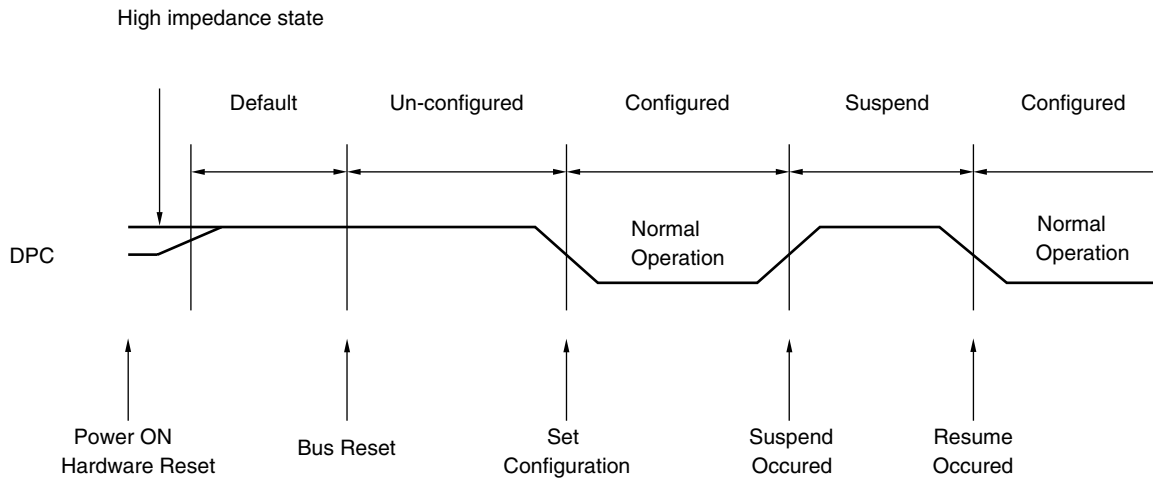
To realize bus-powered or high performance self-powered USB2.0 to IDE Bridge system, the μPD720130 has two internal system clock mode. One is 7.5 MHz for bus-powered mode and the other is 60 MHz for self-powered mode. The μPD720130 controls the power state by events as follows. The word with under line shows event. The italic word shows the power state.

Figure 2-3. Power State Control



To realize bus-powered USB2.0 to IDE Bridge system, the power consumption for IDE device should be controlled by the power state of the μPD720130. The μPD720130 has DPC pin to control IDE device's power circuit. DPC pin's output level relates to USB device states. DPC should be pull up to 3.3 V because DPC output becomes high impedance state until the μPD720130 is initialized.

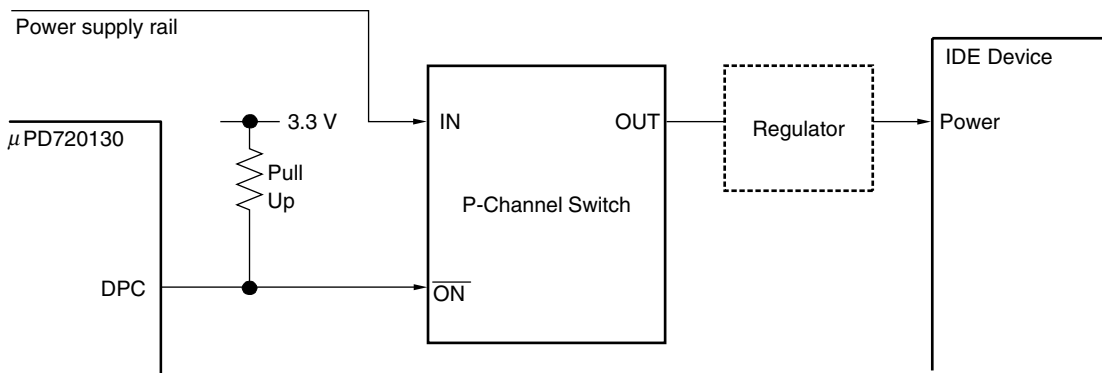
Figure 2-4. DPC Pin to Control IDE Device's Power Circuit



Following reference circuit can cut off power supply to IDE device during the μPD720130 is under default and un-configured state. Also, the power supply to IDE device is disabled during suspend state, too.

Power consumption of total system under default, un-configured, and suspend state can be reduced by DPC pin.

Figure 2-5. Power Control Circuit Example



3. ELECTRICAL SPECIFICATIONS

3.1 Buffer List

- 2.5 V oscillator interface
XIN, XOUT
- 3.3 V input buffer
MD(1:0), TEST(3:0), SMC
- 3.3 V schmitt input buffer
RESETB, IRQ0
- 3.3 V input buffer with enable (OR type)
DCC, DV(1:0), SPD, CLC, PWR, CMB_STATE
- 3.3 V $I_{OL} = 6$ mA 3-state output buffer
CMB_BSY, DPC
- 3.3 V $I_{OL} = 3$ mA bi-directional schmitt buffer with input enable (OR-type)
GPIO(7:0), PIO5, SDA, SCL
- 3.3 V $I_{OL} = 6$ mA bi-directional buffer with input enable (OR-type)
PIO(15:14)
- 5 V schmitt input buffer
VBUS
- 5 V $I_{OL} = 6$ mA 3-state output buffer
IDECS(1:0)B, IDEA(2:0), IDEDAKB, IDEIORB, IDEIOWB, IDERSTB
- 5 V $I_{OL} = 6$ mA bi-directional buffer with input enable (OR-type)
IDED(15:0), IDEINT, IDEIORDY, IDEDRQ
- USB interface
DP, DM, RSDP, RSDM, RREF, RPU

Remark Above, “5 V” refers to a 3.3 V buffer with 5-V tolerant circuit. Therefore, it is possible to have a 5-V connection for an external bus, but the output level will be only up to 3.3 V, which is the V_{DD33} voltage.

3.2 Terminology

Terms Used in Absolute Maximum Ratings

Parameter	Symbol	Meaning
Power supply voltage	V_{DD33}, V_{DD25}	Indicates voltage range within which damage or reduced reliability will not result when power is applied to a V_{DD} pin.
Input voltage	V_i	Indicates voltage range within which damage or reduced reliability will not result when power is applied to an input pin.
Output voltage	V_o	Indicates voltage range within which damage or reduced reliability will not result when power is applied to an output pin.
Output current	I_o	Indicates absolute tolerance value for DC current to prevent damage or reduced reliability when a current flows out of or into an output pin.
Operating temperature	T_A	Indicates the ambient temperature range for normal logic operations.
Storage temperature	T_{stg}	Indicates the element temperature range within which damage or reduced reliability will not result while no voltage or current are applied to the device.

Terms Used in Recommended Operating Range

Parameter	Symbol	Meaning
Power supply voltage	V_{DD33}, V_{DD25}	Indicates the voltage range for normal logic operations occur when $V_{SS} = 0 V$.
High-level input voltage	V_{IH}	Indicates the voltage, which is applied to the input pins of the device, is the voltage indicates that the high level states for normal operation of the input buffer. * If a voltage that is equal to or greater than the "Min." value is applied, the input voltage is guaranteed as high level voltage.
Low-level input voltage	V_{IL}	Indicates the voltage, which is applied to the input pins of the device, is the voltage indicates that the low level states for normal operation of the input buffer. * If a voltage that is equal to or lesser than the "Max." value is applied, the input voltage is guaranteed as low level voltage.
Hysteresys voltage	V_H	Indicates the differential between the positive trigger voltage and the negative trigger voltage.
Input rise time	t_{ri}	Indicates allowable input rise time to input pins. Input rise time is transition time from $0.1 \times V_{DD}$ to $0.9 \times V_{DD}$.
Input fall time	t_{fi}	Indicates allowable input fall time to input pins. Input fall time is transition time from $0.9 \times V_{DD}$ to $0.1 \times V_{DD}$.

Terms Used in DC Characteristics

Parameter	Symbol	Meaning
Off-state output leakage current	I_{oz}	Indicates the current that flows from the power supply pins when the rated power supply voltage is applied when a 3-state output has high impedance.
Output short circuit current	I_{os}	Indicates the current that flows when the output pin is shorted (to GND pins) when output is at high-level.
Input leakage current	I_i	Indicates the current that flows when the input voltage is supplied to the input pin.
Low-level output current	I_{oL}	Indicates the current that flows to the output pins when the rated low-level output voltage is being applied.
High-level output current	I_{oH}	Indicates the current that flows from the output pins when the rated high-level output voltage is being applied.

3.3 Electrical Specifications

Absolute Maximum Ratings

Parameter	Symbol	Condition	Rating	Unit
Power supply voltage	V _{DD33}	3.3 V power supply rail	-0.5 to +4.6	V
	V _{DD25}	2.5 V power supply rail	-0.5 to +3.6	V
Input voltage, 5 V buffer	V _I	3.0 V ≤ V _{DD33} ≤ 3.6 V V _I < V _{DD33} + 3.0 V	-0.5 to +6.6	V
Input voltage, 3.3 V buffer	V _I	3.0 V ≤ V _{DD33} ≤ 3.6 V V _I < V _{DD33} + 1.0 V	-0.5 to +4.6	V
Input voltage, 2.5 V buffer	V _I	2.3 V ≤ V _{DD25} ≤ 2.7 V V _I < V _{DD25} + 0.9 V	-0.5 to +3.6	V
Output voltage, 5 V buffer	V _O	3.0 V ≤ V _{DD33} ≤ 3.6 V V _O < V _{DD33} + 3.0 V	-0.5 to +6.6	V
Output voltage, 3.3 V buffer	V _O	3.0 V ≤ V _{DD33} ≤ 3.6 V V _O < V _{DD33} + 1.0 V	-0.5 to +4.6	V
Output voltage, 2.5 V buffer	V _O	2.3 V ≤ V _{DD25} ≤ 2.7 V V _O < V _{DD25} + 0.9 V	-0.5 to +3.6	V
Output current, 5 V buffer	I _O	I _{OL} = 6 mA	20	mA
Output current, 3.3 V buffer	I _O	I _{OL} = 6 mA	20	mA
		I _{OL} = 3 mA	10	mA
Operating ambient temperature	T _A		0 to +70	°C
Storage temperature	T _{stg}		-65 to +150	°C

Caution Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameters. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.

The ratings and conditions indicated for DC characteristics and AC characteristics represent the quality assurance range during normal operation.

Two Power Supply Rails Limitation

The μPD720130 has two power supply rails (2.5 V, 3.3 V). The system will require the time when power supply rail is stable at V_{DD} level. And, there will be difference between the time of V_{DD25} and V_{DD33}. The μPD720130 requires that V_{DD25} should be stable before V_{DD33} becomes stable. At this case, the system must ensure that the absolute maximum ratings for V_I / V_O are not exceeded. System reset signaling should be asserted more than specified time after both V_{DD25} and V_{DD33} are stable.

Recommended Operating Ranges

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Operating voltage	V _{DD33}	3.3 V for V _{DD33} pins	3.0	3.3	3.6	V
	V _{DD25}	2.5 V for V _{DD25} pins	2.3	2.5	2.7	V
	V _{DD25}	2.5 V for AV _{DD25} pins	2.3	2.5	2.7	V
High-level input voltage	V _{IH}					
5.0 V high-level input voltage			2.0		5.5	V
3.3 V high-level input voltage			2.0		V _{DD33}	V
2.5 V high-level input voltage			1.7		V _{DD25}	V
Low-level input voltage	V _{IL}					
5.0 V low-level input voltage			0		0.8	V
3.3 V low-level input voltage			0		0.8	V
2.5 V low-level input voltage			0		0.7	V
Hysteresis voltage	V _H					
5 V hysteresis voltage			0.3		1.5	V
3.3 V hysteresis voltage			0.2		1.0	V
Input rise time	t _{ri}					
Normal buffer			0		200	ns
Schmitt buffer			0		10	ms
Input fall time	t _{fi}					
Normal buffer			0		200	ns
Schmitt buffer			0		10	ms

DC Characteristics (V_{DD33} = 3.0 to 3.6 V, V_{DD25} = 2.3 to 2.7 V, T_A = 0 to +70°C)

Control Pin Block

Parameter	Symbol	Condition	Min.	Max.	Unit
Off-state output current	I _{OZ}	V _O = V _{DD33} , V _{DD25} or V _{SS}		±10	μA
Output short circuit current	I _{OS} ^{Note}			-250	mA
Low-level output current	I _{OL}				
5.0 V low-level output current		V _{OL} = 0.4 V	6.0		mA
3.3 V low-level output current		V _{OL} = 0.4 V	6.0		mA
3.3 V low-level output current		V _{OL} = 0.4 V	3.0		mA
High-level output current	I _{OH}				
5.0 V high-level output current		V _{OH} = 2.4 V	-2.0		mA
3.3 V high-level output current		V _{OH} = 2.4 V	-6.0		mA
3.3 V high-level output current		V _{OH} = 2.4 V	-3.0		mA
Input leakage current	I _I				
3.3 V buffer		V _I = V _{DD} or V _{SS}		±10	μA
5.0 V buffer		V _I = V _{DD} or V _{SS}		±10	μA

Note The output short circuit time is one second or less and is only for one pin on the LSI.

USB Interface Block

Parameter	Symbol	Conditions	Min.	Max.	Unit
Serial Resistor between DP (DM) and RSDP (RSDM)	R _S		38.61	39.39	Ω
Output pin impedance	Z _{HSDRV}	Includes R _S resistor	40.5	49.5	Ω
Bus pull-up resistor on upstream facing port	R _{PU}	1.5 kΩ ±5% consists of resistance of transistor and pull-up resistor	1.485	1.515	Ω
Termination voltage for upstream facing port pull-up	V _{TERM}		3.0	3.6	V
Input Levels for Full-speed:					
High-level input voltage (drive)	V _{IH}		2.0		V
High-level input voltage (floating)	V _{IHZ}		2.7	3.6	
Low-level input voltage	V _{IL}			0.8	V
Differential input sensitivity	V _{DI}	(D+) – (D-)	0.2		V
Differential common mode range	V _{CM}	Includes V _{DI} range	0.8	2.5	V
Output Levels for Full-speed:					
High-level output voltage	V _{OH}	R _L of 14.25 kΩ to V _{SS}	2.8	3.6	V
Low-level output voltage	V _{OL}	R _L of 1.425 kΩ to 3.6 V	0.0	0.3	V
SE1	V _{OSE1}		0.8		V
Output signal crossover point voltage	V _{CRS}		1.3	2.0	V
Input Levels for High-speed:					
High-speed squelch detection threshold (differential signal)	V _{HSSQ}		100	150	mV
High-speed disconnect detection threshold (differential signal)	V _{HSDSC}		525	625	mV
High-speed data signaling common mode voltage range	V _{HSCM}		-50	+500	mV
High-speed differential input signaling level	See Figure 3-4 .				
Output Levels for High-speed:					
High-speed idle state	V _{HSOI}		-10.0	+10.0	mV
High-speed data signaling high	V _{HSOH}		360	440	mV
High-speed data signaling low	V _{H SOL}		-10.0	+10.0	mV
Chirp J level (differential signal)	V _{CHIRPJ}		700	1100	mV
Chirp K level (differential signal)	V _{CHIRPK}		-900	-500	mV

Figure 3-1. Differential Input Sensitivity Range for Low-/full-speed

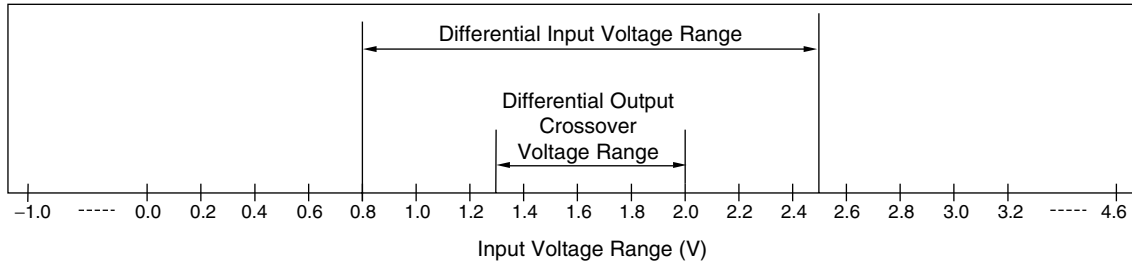


Figure 3-2. Full-speed Buffer V_{OH}/I_{OH} Characteristics for High-speed Capable Transceiver

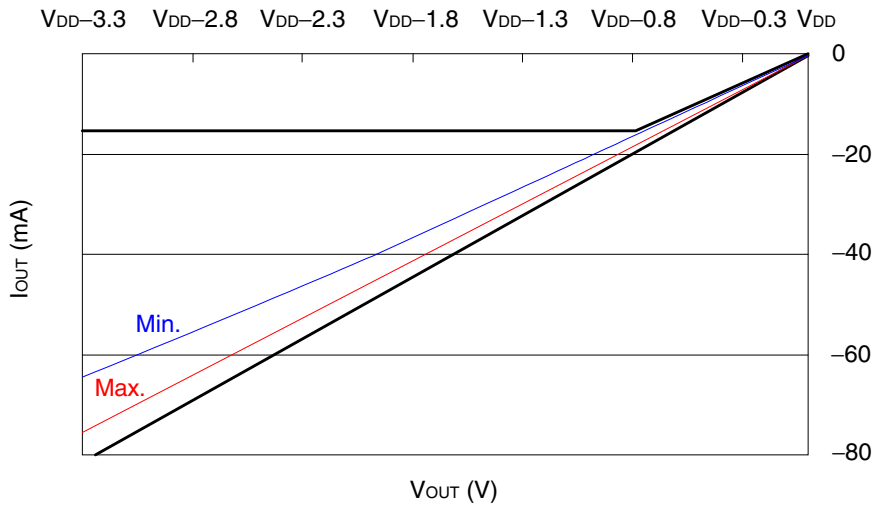


Figure 3-3. Full-speed Buffer V_{OL}/I_{OL} Characteristics for High-speed Capable Transceiver

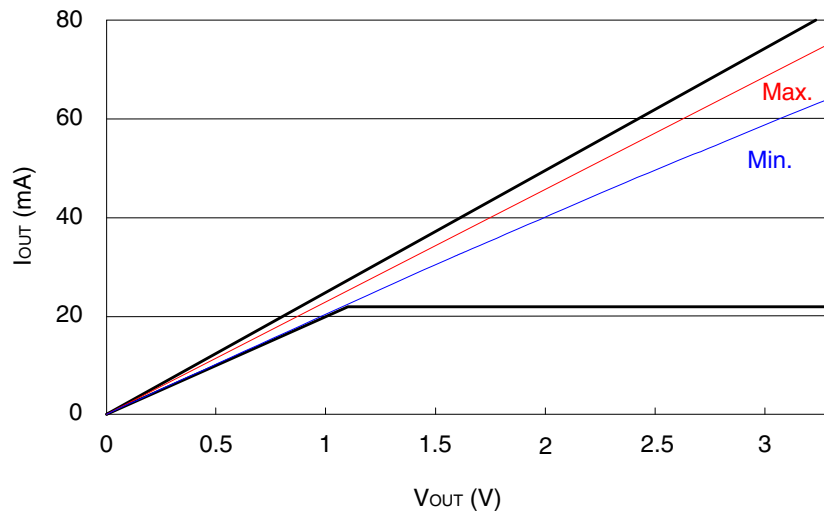


Figure 3-4. Receiver Sensitivity for Transceiver at DP/DM

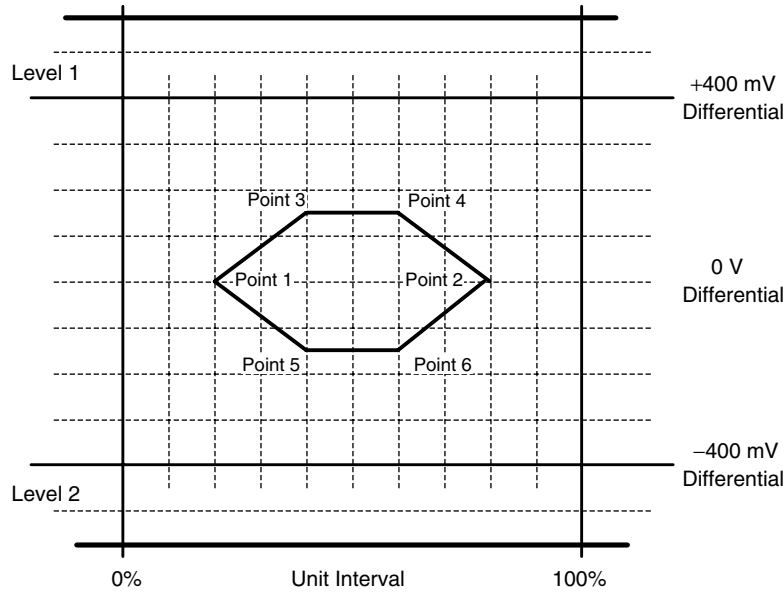
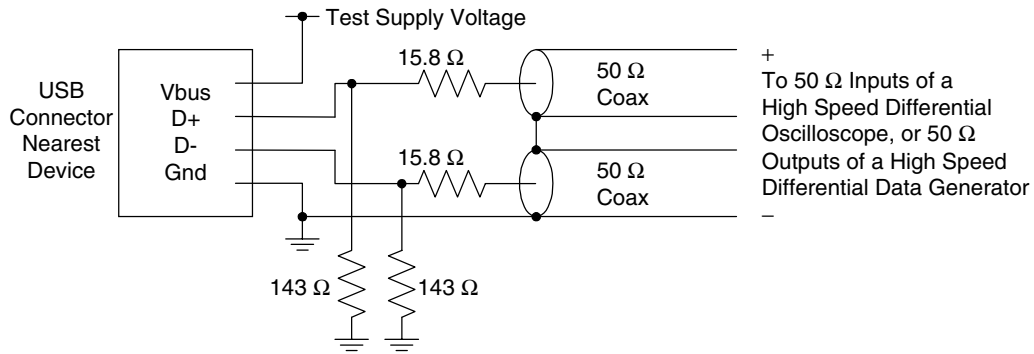


Figure 3-5. Receiver Measurement Fixtures



Pin Capacitance

Parameter	Symbol	Condition	Min.	Max.	Unit
Input capacitance	C _{IN}	V _{DD} = 0 V, T _A = 25°C	4	6	pF
Output capacitance	C _{OUT}	f _c = 1 MHz	4	6	pF
I/O capacitance	C _{IO}	Unmeasured pins returned to 0 V	4	6	pF

Power Consumption

(1) The power consumption when device works as bus-powered mode

Symbol	Condition	Max.			Unit
		V _{DD25}	V _{DD33}	A _{VDD25}	
P _{ENUM-BUS}	The power consumption under unconfigured stage				
	High-speed operating	57	3	10	mA
	Full-speed operating	23	4	10	mA
P _{W-BUS}	The power consumption when device works				
	High-speed operating	110	22	10	mA
	Full-speed operating	113	13	10	mA
P _{W_SPD-BUS}	The power consumption under suspend state	10	235	5	μA

(2) The power consumption when device works as self-powered mode

Symbol	Condition	Max.			Unit
		V _{DD25}	V _{DD33}	A _{VDD25}	
P _{ENUM-SELF}	The power consumption under unconfigured stage				
	High-speed operating	85	5	10	mA
	Full-speed operating	60	5	10	mA
P _{W-SELF}	The power consumption when device works				
	High-speed operating	120	25	10	mA
	Full-speed operating	113	13	10	mA
P _{W_SPD-SELF}	The power consumption under suspend state	50	5	5	mA
P _{W_UNP}	The power consumption under unplug state	87	3	10	mA
P _{W_COM}	The power consumption under combo mode The device is releasing the IDE bus.	90	5	10	mA

AC Characteristics (VDD33 = 3.0 to 3.6 V, VDD25 = 2.3 to 2.7 V, TA = 0 to +70°C)

System Clock Ratings

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Clock frequency	f _{CLK}	X'tal	-500 ppm	30	+500 ppm	MHz
		Oscillator block	-500 ppm	30	+500 ppm	MHz
Clock duty cycle	t _{DUTY}		45	50	55	%

- Remarks**
1. Recommended accuracy of clock frequency is ± 100 ppm.
 2. Required accuracy of X'tal or Oscillator block is including initial frequency accuracy, the spread of X'tal capacitor loading, supply voltage, temperature, and aging, etc.

System Reset signaling

Parameter	Symbol	Conditions	Min.	Max.	Unit
Reset active time	t _{rst}		2		μs

USB Interface Block

(1/2)

Parameter	Symbol	Conditions	Min.	Max.	Unit
Full-speed Source Electrical Characteristics					
Rise time (10% - 90%)	t _{FR}	C _L = 50 pF, R _s = 36 Ω	4	20	ns
Fall time (90% - 10%)	t _{FF}	C _L = 50 pF, R _s = 36 Ω	4	20	ns
Differential rise and fall time matching	t _{FRFM}	(t _{FR} /t _{FF})	90	111.11	%
Full-speed data rate for device which are high-speed capable	t _{FDRATHS}	Average bit rate	11.9940	12.0060	Mbps
Frame interval	t _{FRAME}		0.9995	1.0005	ms
Consecutive frame interval jitter	t _{RFI}	No clock adjustment		42	ns
Source jitter total (including frequency tolerance):					
To next transition	t _{DJ1}		-3.5	+3.5	ns
For paired transitions	t _{DJ2}		-4.0	+4.0	ns
Source jitter for differential transition to SE0 transition	t _{FDEOP}		-2	+5	ns
Receiver jitter:					
To next transition	t _{JR1}		-18.5	+18.5	ns
For paired transitions	t _{JR2}		-9	+9	ns
Source SE0 interval of EOP	t _{FEOPT}		160	175	ns
Receiver SE0 interval of EOP	t _{FEOPR}		82		ns
Width of SE0 interval during differential transition	t _{FST}			14	ns

(2/2)

Parameter	Symbol	Conditions	Min.	Max.	Unit
High-speed Source Electrical Characteristics					
Rise time (10% - 90%)	t _{HSR}		500		ps
Fall time (90% - 10%)	t _{HSF}		500		ps
Driver waveform	See Figure 3-6.				
High-speed data rate	t _{HSDRAT}		479.760	480.240	Mbps
Microframe interval	t _{HSFRAM}		124.9375	125.0625	μs
Consecutive microframe interval difference	t _{HSRFI}			4 high-speed	Bit times
Data source jitter	See Figure 3-6.				
Receiver jitter tolerance	See Figure 3-4.				
Device Event Timings					
Time from internal power good to device pulling D+ beyond V _{IHZ} (min.) (signaling attached)	t _{SIGATT}			100	ms
Debounce interval provided by USB system software after attach	t _{ATTDB}			100	ms
Inter-packet delay for full-speed	t _{IPD}		2		Bit times
Inter-packet delay for device response w/detachable cable for full-speed	t _{RSPDP1}			6.5	Bit times
High-speed detection start time from suspend	t _{SQA}		2.5		μs
Sample time for suspend vs reset	t _{CSR}		100	875	μs
Time to detect bus suspend state	t _{SPD}		3.000	3.125	ms
Power down under suspend	t _{SUS}			10	ms
Reversion time from suspend to high-speed	t _{RHS}			1.333	μs
Drive Chirp K width	t _{CKO}		1		ms
Finish Chirp K assertion	t _{FCA}			7	ms
Start sequencing Chirp K-J-K-J-K-J	t _{SSC}			100	μs
Finish sequencing Chirp K-J	t _{FSC}		-500	-100	μs
Detect sequencing Chirp K-J width	t _{CSI}		2.5		μs
Sample time for sequencing Chirp	t _{SCS}		1	2.5	ms
Reversion time to high-speed	t _{RHA}			500	μs
High-speed detection start time	t _{HDS}		2.5	3000	μs
Reset completed time	t _{DRS}		10		ms

IDE Interface Block

PIO mode

Parameter	Symbol	Mode 0	Mode 1	Mode 2	Mode 3	Mode 4	Unit
Cycle time (min.)	t ₀	600	383	240	180	120	ns
Address setup time (min.)	t ₁	70	50	30	30	25	ns
16 bits DIOR/DIOW pulse width (min.)	t ₂	165	125	100	80	70	ns
8 bits DIOR/DIOW pulse width (min.)		290	290	290	80	70	ns
DIOR/DIOW recovery time (min.)	t _{2i}	–	–	–	70	25	ns
DIOW data setup time (min.)	t ₃	60	45	30	30	20	ns
DIOW data hold time (min.)	t ₄	30	20	15	10	10	ns
DIOR data setup time (min.)	t ₅	50	35	20	20	20	ns
DIOR data hold time (min.)	t ₆	5	5	5	5	5	ns
DIOR 3-state delay time (max.)	t _{6Z}	30	30	30	30	30	ns
Address hold time (min.)	t ₉	20	15	10	10	10	ns
IORDY read data valid time (min.) ^{Note}	t _{RD}	0	0	0	0	0	ns
IORDY setup time (min.) ^{Note}	t _A	35	35	35	35	35	ns
IORDY pulse width (max.) ^{Note}	t _B	1250	1250	1250	1250	1250	ns
IORDY Inactive to Hi-Z time (max.) ^{Note}	t _C	5	5	5	5	5	ns

Note IORDY is an option in mode 0 - 2. IORDY is essential in modes 3 and 4.

Multi Word DMA mode

Parameter	Symbol	Mode 0	Mode 1	Mode 2	Unit
Cycle time (min.)	t ₀	480	150	120	ns
DIOR/DIOW pulse width (min.)	t _D	215	80	70	ns
DIOR data access time (max.)	t _E	150	60	50	ns
DIOR data hold time (min.)	t _F	5	5	5	ns
DIOR data setup time (min.)	t _{Gr}	100	30	20	ns
DIOW data setup time (min.)	t _{Gw}	100	30	20	ns
DIOW data hold time (min.)	t _H	20	15	10	ns
DMACK setup time (min.)	t _I	0	0	0	ns
DMACK hold time (min.)	t _J	20	5	5	ns
DIOR negate pulse width (min.)	t _{Kr}	50	50	25	ns
DIOW negate pulse width (min.)	t _{Kw}	215	50	25	ns
DIOR-DMARQ delay time (max.)	t _{Lr}	120	40	35	ns
DIOW-DMARQ delay time (max.)	t _{Lw}	40	40	35	ns
DMACK 3-state delay time (max.)	t _Z	20	25	25	ns
CS setup time (min.)	t _M	50	30	25	ns
CS hold time (min.)	t _N	15	10	10	ns

Ultra DMA mode

Parameter	Symbol	Mode 0		Mode 1		Mode 2		Mode 3		Mode 4		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
Average cycle time for 2 cycles	t _{2CYC}	240	-	160	-	120	-	90	-	60	-	ns
Minimum cycle time for 2 cycles	t _{2CYC}	235	-	156	-	117	-	86	-	57	-	ns
Cycle time for 1 cycle	t _{CYC}	114	-	75	-	55	-	39	-	25	-	ns
Data setup time on receive side	t _{DS}	15	-	10	-	7	-	7	-	5	-	ns
Data hold time on receive side	t _{DH}	5	-	5	-	5	-	5	-	5	-	ns
Data setup time on transmit side	t _{DVS}	70	-	48	-	34	-	20	-	6	-	ns
Data hold time on transmit side	t _{DVH}	6	-	6	-	6	-	6	-	6	-	ns
First STROBE time	t _{FS}	0	230	0	200	0	170	0	130	0	120	ns
Interlock time with limitation	t _{LI}	0	150	0	150	0	150	0	100	0	100	ns
Minimum interlock time	t _{MLI}	20	-	20	-	20	-	20	-	20	-	ns
Interlock time without limitation	t _{UI}	0	-	0	-	0	-	0	-	0	-	ns
Output release time	t _{AZ}	-	10	-	10	-	10	-	10	-	10	ns
Output delay time	t _{ZAH}	20	-	20	-	20	-	20	-	20	-	ns
Output stabilization time (from release)	t _{ZAD}	0	-	0	-	0	-	0	-	0	-	ns
Envelope time	t _{ENV}	20	70	20	70	20	70	20	55	20	55	ns
STROBE DMARDY delay time	t _{SR}	-	50	-	30	-	20	-	NA	-	NA	ns
Last STROBE time	t _{RFS}	-	75	-	60	-	50	-	60	-	60	ns
Pause time	t _{RP}	160	-	125	-	100	-	100	-	100	-	ns
IORDY pull-up time	t _{IORYZ}	-	20	-	20	-	20	-	20	-	20	ns
IORDY wait time	t _{ZIORY}	0	-	0	-	0	-	0	-	0	-	ns
DMACK setup/hold time	t _{ACK}	20	-	20	-	20	-	20	-	20	-	ns
STROBE STOP time	t _{SS}	50	-	50	-	50	-	50	-	50	-	ns

Serial ROM interface Block

Parameter	Symbol	Conditions	Min.	Max.	Unit
Clock frequency	t_{SCL}			100	KHz
Clock pulse width low	t_{LOW}		4.7		μ s
Clock pulse width high	t_{HIGH}		4.0		μ s
Clock Low to data valid	t_{AA}		100	4500	ns
Start hold time	$t_{HD.STA}$		4.0		μ s
Start setup time	$t_{SU.STA}$		4.7		μ s
Data in hold time	$t_{HD.DAT}$		0		ns
Data in setup time	$t_{SU.DAT}$		0.2		μ s
Data out hold time	t_{DH}		50		ns
Stop setup time	$t_{SU.STO}$		4.7		μ s
Time the bus must be free before a new transmission can start	t_{BUF}		10		μ s
Write cycle time	t_{WR}		10		ms

Figure 3-6. Transmit Waveform for Transceiver at DP/DM

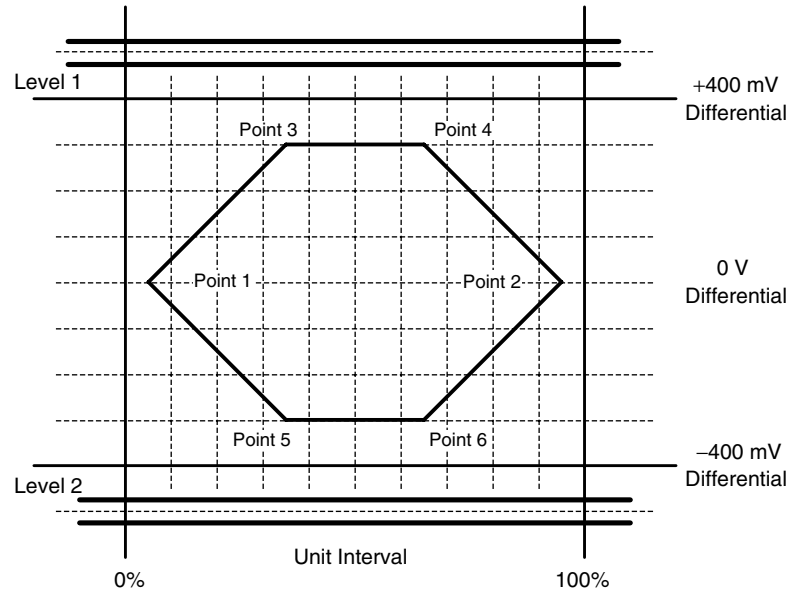
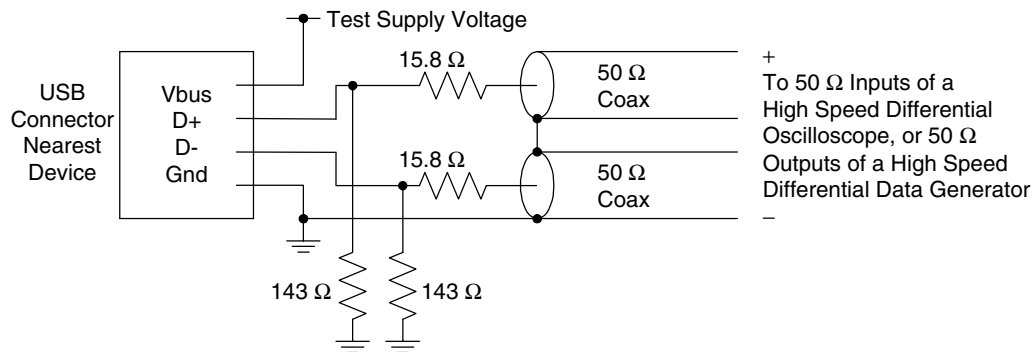
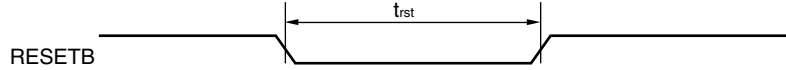


Figure 3-7. Transmitter Measurement Fixtures



Timing Diagram

System reset timing

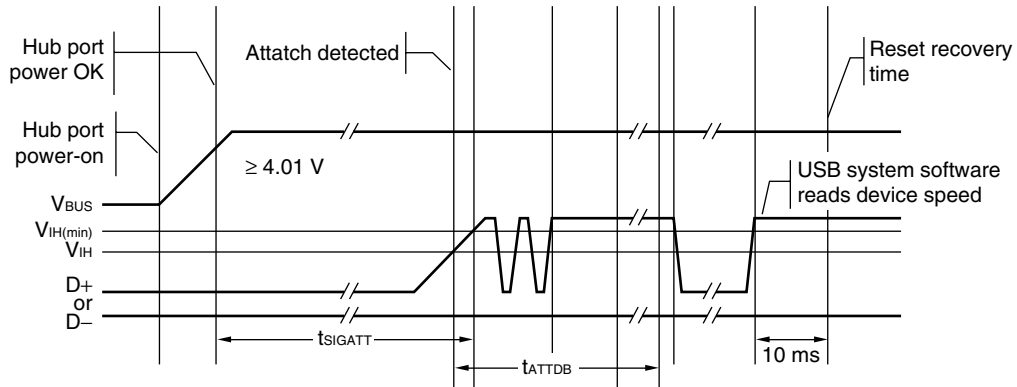


Remark After RESET is negated, this chip read the serial ROM first. Do not reset while the serial ROM is read. The serial ROM is completed to read below time, after RESET is negated.

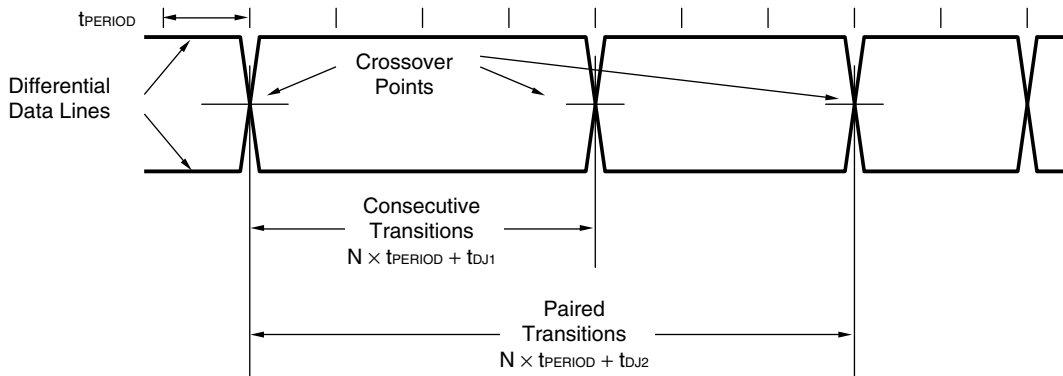
$$5 + 0.1197 \times \text{bytes (serial ROM size)} + 0.5678 \text{ (ms)}$$

Example In the case of 512 bytes: 66.855 ms, in the case of 8 Kbytes: 986.15 ms

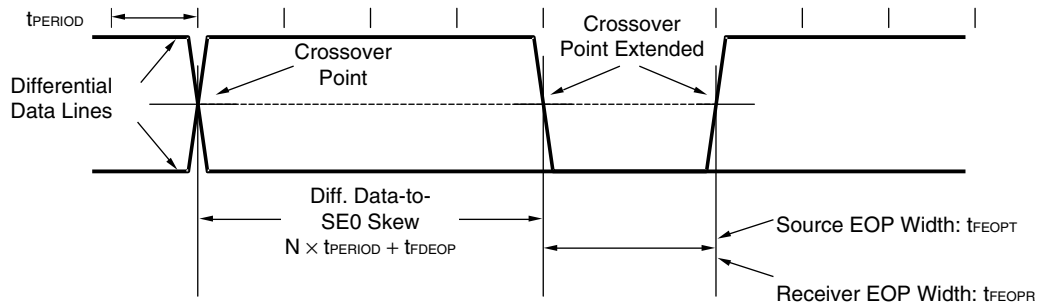
USB power-on and connection events



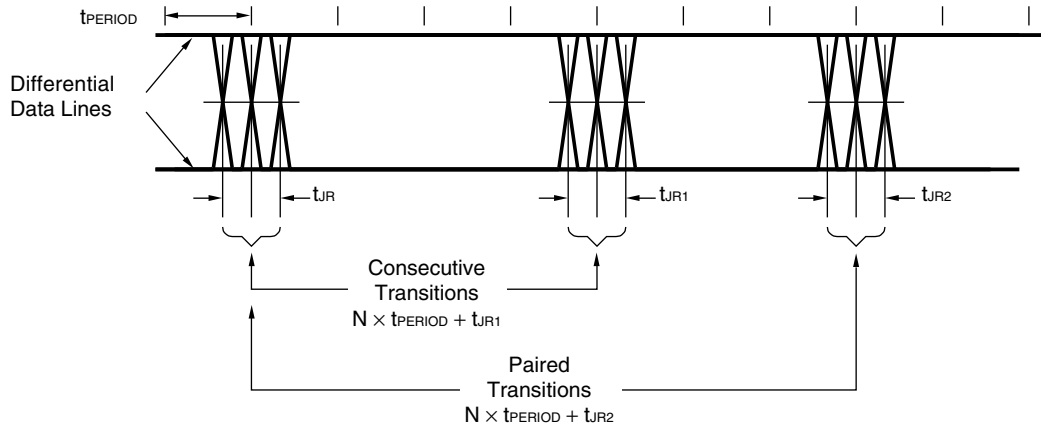
USB differential data jitter for full-speed



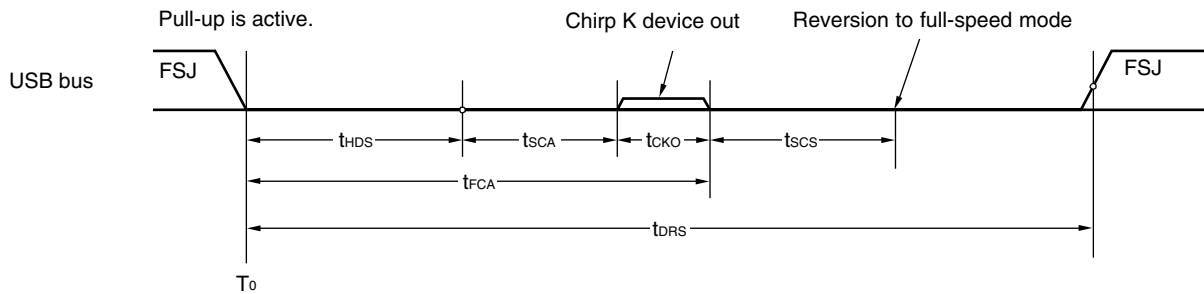
USB differential-to-EOP transition skew and EOP width for full-speed



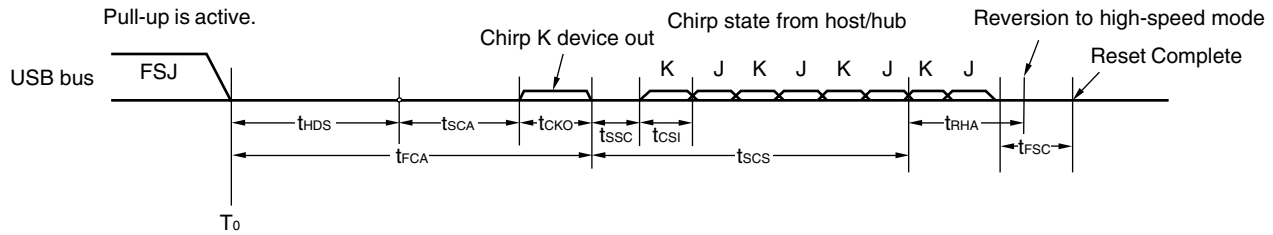
USB receiver jitter tolerance for full-speed



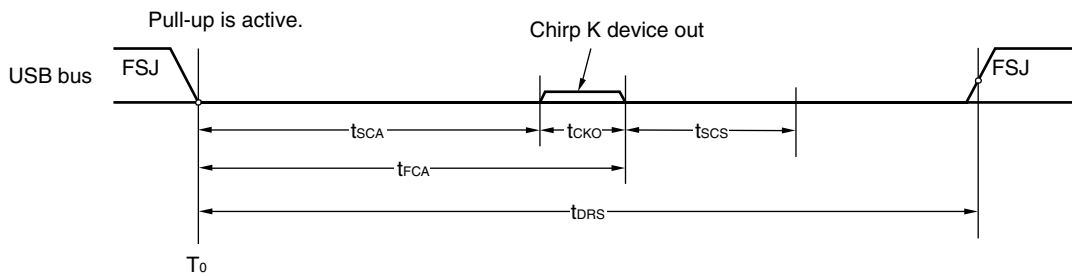
USB connection sequence on full-speed system bus



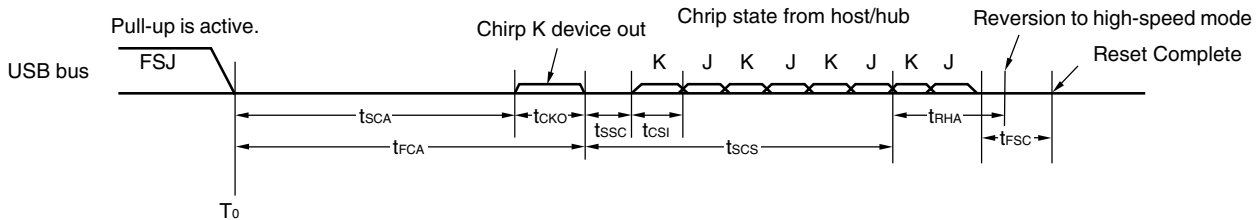
USB connection sequence on high-speed system bus



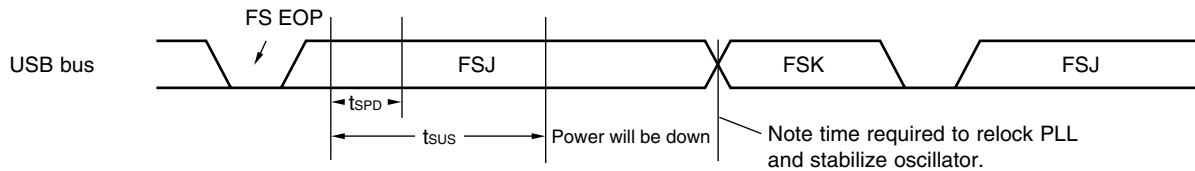
USB reset sequence from suspend state on full-speed system bus



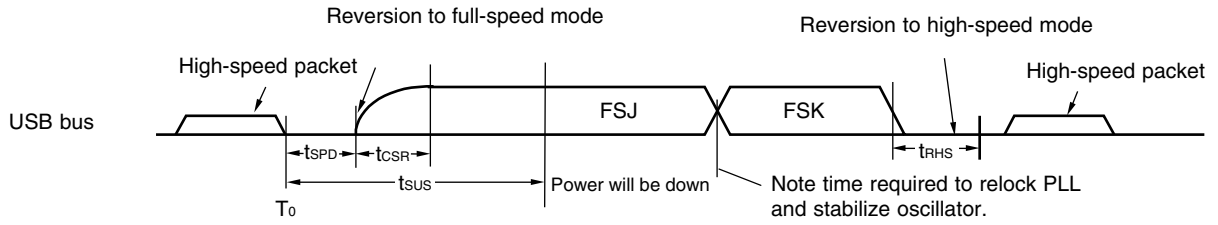
USB reset sequence from suspend state on high-speed system bus



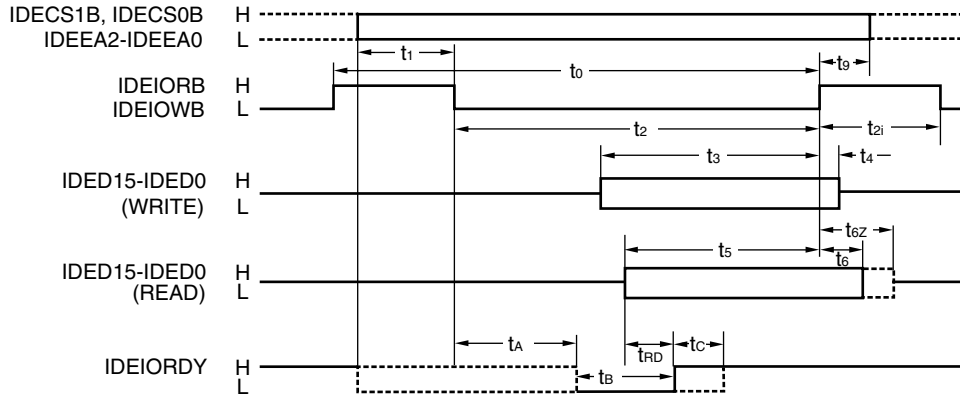
USB suspend and resume on full-speed system bus



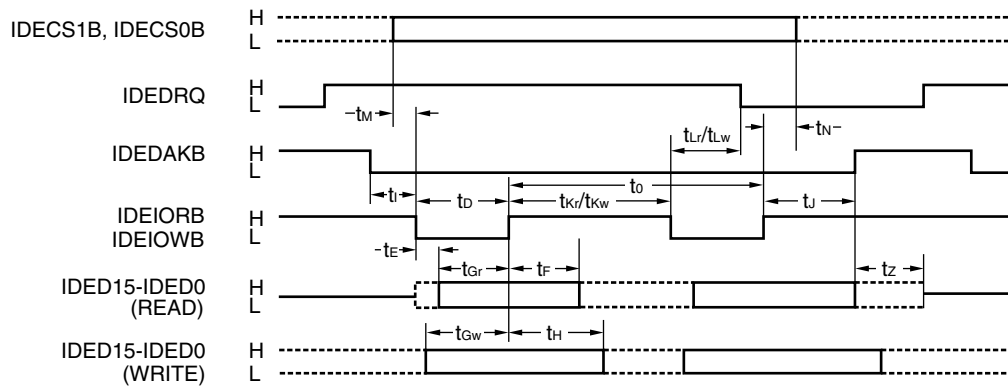
USB suspend and resume on high-speed system bus



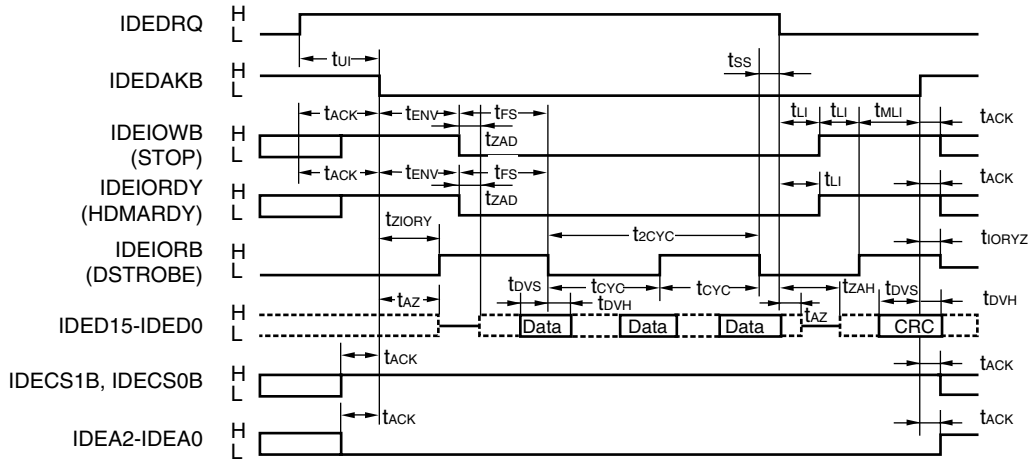
IDE PIO mode timing



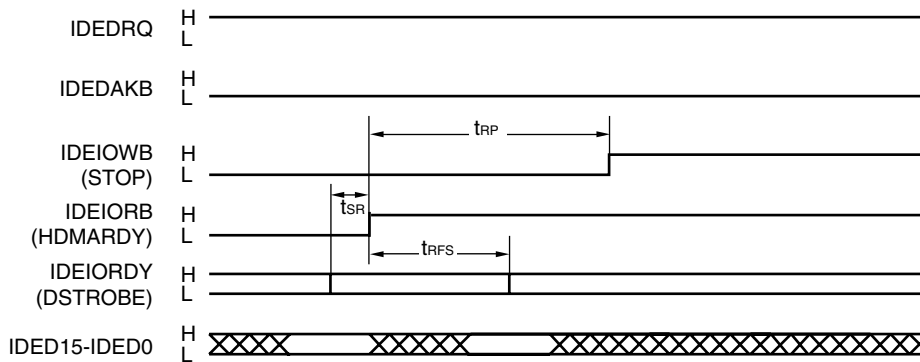
IDE multi word DMA mode timing



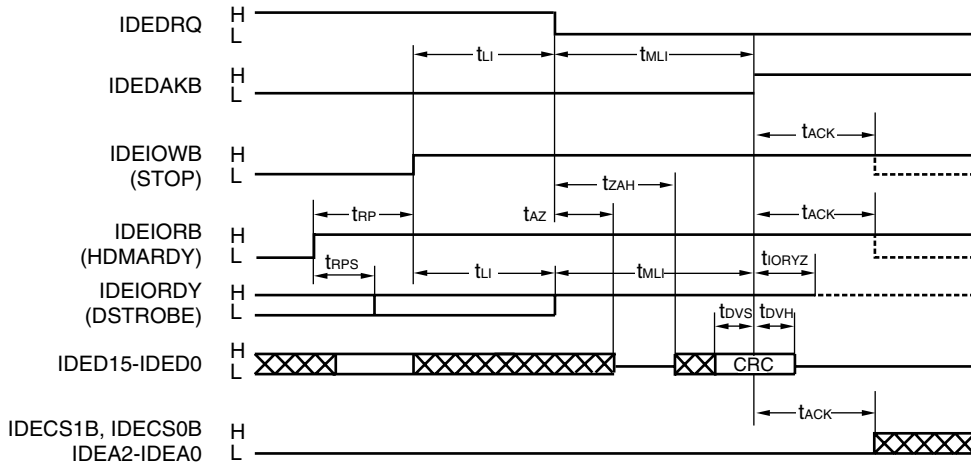
IDE ultra DMA mode data-in timing



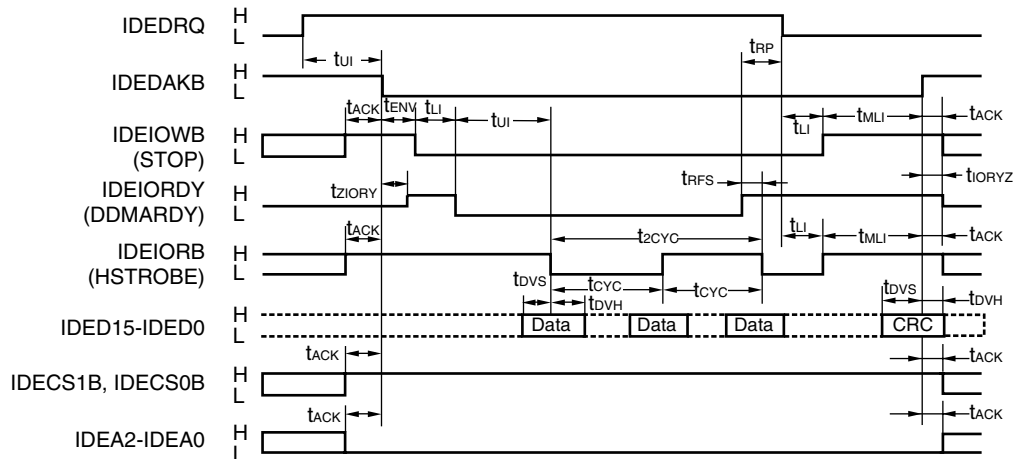
IDE ultra DMA mode data-in stop timing



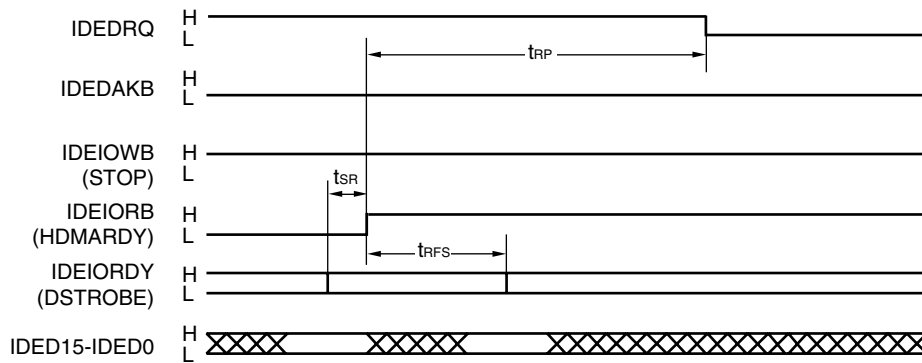
IDE ultra DMA mode data-in end timing



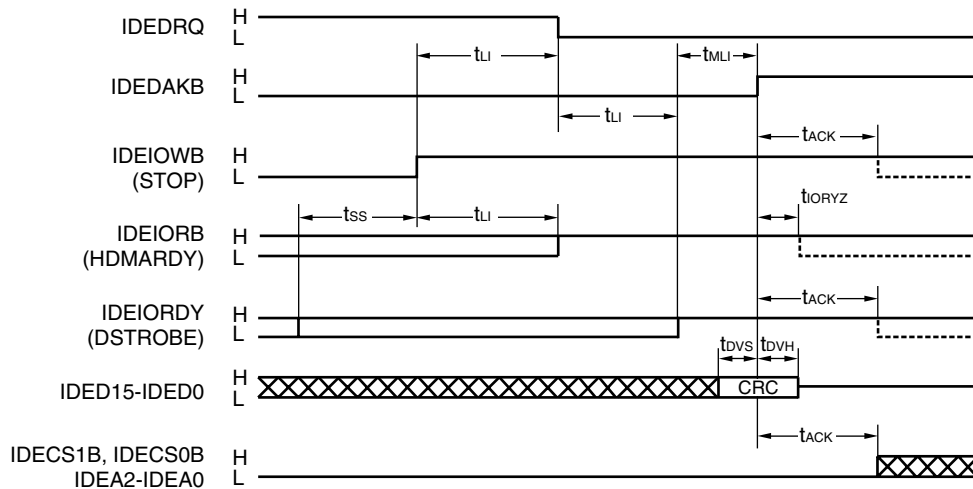
IDE ultra DMA mode data-out timing



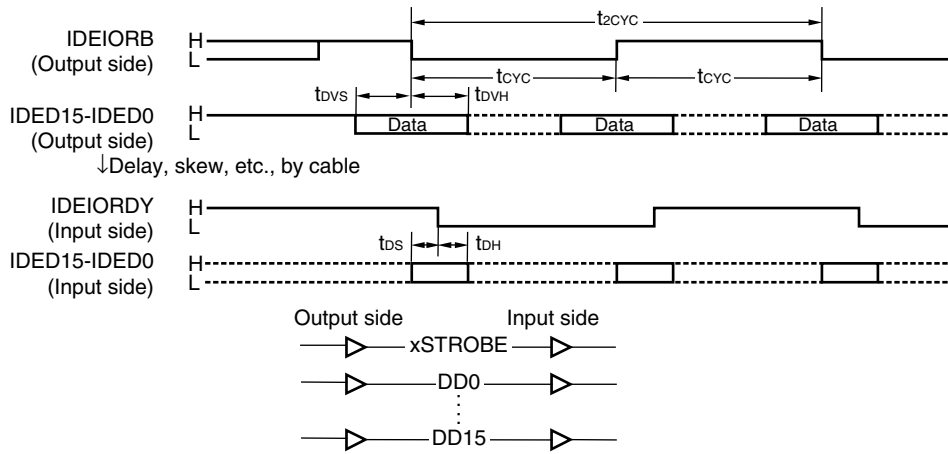
IDE ultra DMA mode data-out stop timing



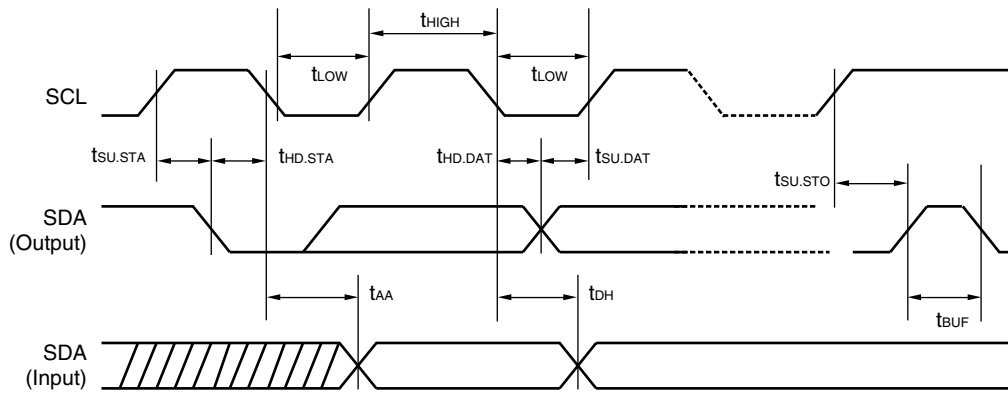
IDE ultra DMA mode data-out end timing



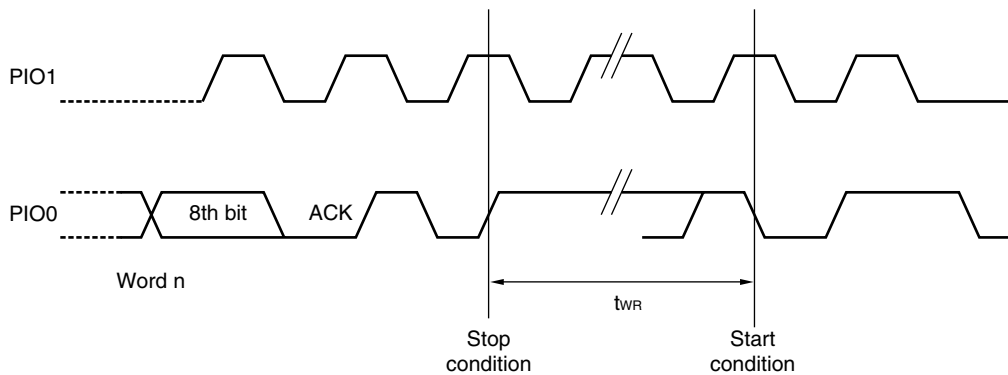
IDE ultra DMA mode data skew timing



Serial ROM access timing



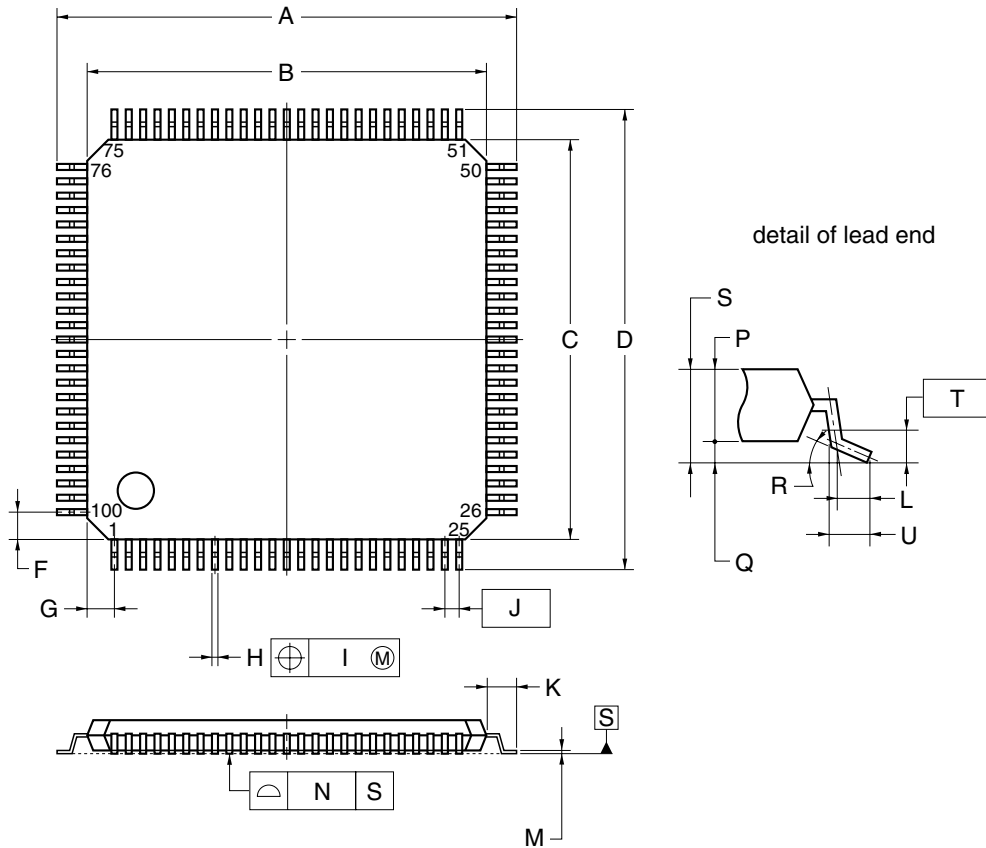
Serial ROM write cycle timing



4. PACKAGE DRAWING

- μPD720130GC-9EU
- ★ • μPD720130GC-9EU-A

100-PIN PLASTIC TQFP (FINE PITCH) (14x14)



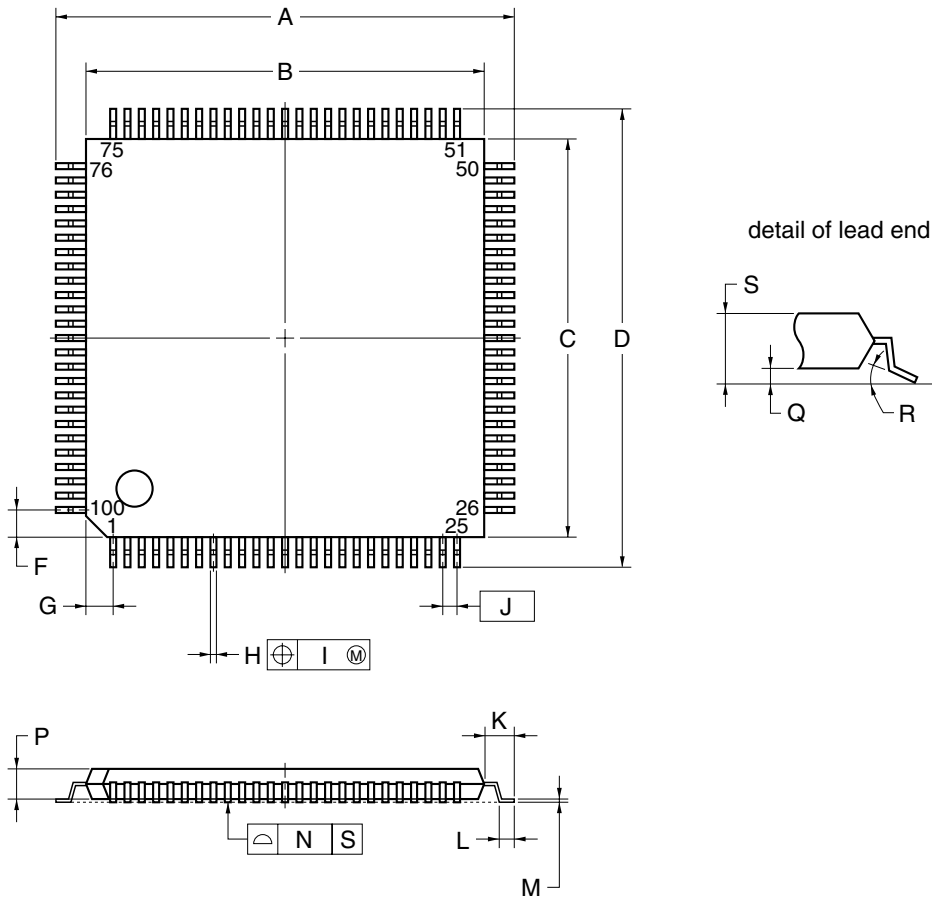
NOTE
 Each lead centerline is located within 0.08 mm of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS
A	16.0±0.2
B	14.0±0.2
C	14.0±0.2
D	16.0±0.2
F	1.0
G	1.0
H	0.22±0.05
I	0.08
J	0.5 (T.P.)
K	1.0±0.2
L	0.5
M	0.17 ^{+0.03} _{-0.07}
N	0.08
P	1.0
Q	0.1±0.05
R	3° ^{+4°} _{-3°}
S	1.1±0.1
T	0.25
U	0.6±0.15

P100GC-50-9EU

• μPD720130GC-9EU-SIN

100-PIN PLASTIC TQFP (FINE PITCH) (14x14)



NOTE

Each lead centerline is located within 0.10 mm of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS
A	16.0±0.2
B	14.0±0.2
C	14.0±0.2
D	16.0±0.2
F	1.0
G	1.0
H	0.22 ^{+0.05} _{-0.04}
I	0.10
J	0.5 (T.P.)
K	1.0±0.2
L	0.5±0.2
M	0.145 ^{+0.055} _{-0.045}
N	0.10
P	1.0±0.1
Q	0.1±0.05
R	3° ^{+7°} _{-3°}
S	1.27 MAX.

S100GC-50-9EU-2

5. RECOMMENDED SOLDERING CONDITIONS

The μPD720130 should be soldered and mounted under the following recommended conditions.

For soldering methods and conditions other than those recommended below, contact your NEC Electronics sales representative.

For technical information, see the following website.

Semiconductor Device Mount Manual (<http://www.necel.com/pkg/en/mount/index.html>)

Recommended Soldering Conditions of Surface-Mount Type

μPD720130GC-9EU: 100-pin plastic TQFP (Fine pitch) (14 × 14)

μPD720130GC-9EU-SIN: 100-pin plastic TQFP (Fine pitch) (14 × 14)

Soldering Method	Soldering Conditions	Symbol
Infrared ray reflow	Peak package's surface temperature :235° C, Reflow time: 30 seconds or less (210 °C or higher), Maximum allowable number of reflow processes: 2, Exposure limit ^{Note} : 3 days (10 hours pre-backing is required at 125C° afterwards). <Caution> Non-heat-resistant trays, such as magazine and taping trays, cannot be baked before unpacking.	IR35-103-2
Partial heating method	Pin temperature: 300°C or below, Heat time: 3 seconds or less (per each side of the device).	-

★

Note The Maximum number of days during which the product can be stored at a temperature of 25°C and a relative humidity of 65% or less after dry-pack package is opened.

★

μPD720130GC-9EU-A: 100-pin plastic TQFP (Fine pitch) (14 × 14)

Soldering Method	Soldering Conditions	Symbol
Infrared ray reflow	Peak package's surface temperature :235° C, Reflow time: 30 seconds or less (210 °C or higher), Maximum allowable number of reflow processes: 2, Exposure limit ^{Note} : 3 days (10 hours pre-backing is required at 125C° afterwards), Flux: Rosin flux with low chlorine (0.2 Wt% or below) recommended. <Caution> Non-heat-resistant trays, such as magazine and taping trays, cannot be baked before unpacking.	IR35-103-2
Partial heating method	Pin temperature: 300°C or below, Heat time: 3 seconds or less (per each side of the device).	-

Note The Maximum number of days during which the product can be stored at a temperature of 25°C and a relative humidity of 65% or less after dry-pack package is opened.

[MEMO]

[MEMO]

[MEMO]

NOTES FOR CMOS DEVICES

① VOLTAGE APPLICATION WAVEFORM AT INPUT PIN

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (MAX) and V_{IH} (MIN) due to noise, etc., the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (MAX) and V_{IH} (MIN).

② HANDLING OF UNUSED INPUT PINS

Unconnected CMOS device inputs can be cause of malfunction. If an input pin is unconnected, it is possible that an internal input level may be generated due to noise, etc., causing malfunction. CMOS devices behave differently than Bipolar or NMOS devices. Input levels of CMOS devices must be fixed high or low by using pull-up or pull-down circuitry. Each unused pin should be connected to V_{DD} or GND via a resistor if there is a possibility that it will be an output pin. All handling related to unused pins must be judged separately for each device and according to related specifications governing the device.

③ PRECAUTION AGAINST ESD

A strong electric field, when exposed to a MOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it when it has occurred. Environmental control must be adequate. When it is dry, a humidifier should be used. It is recommended to avoid using insulators that easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors should be grounded. The operator should be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions need to be taken for PW boards with mounted semiconductor devices.

④ STATUS BEFORE INITIALIZATION

Power-on does not necessarily define the initial status of a MOS device. Immediately after the power source is turned ON, devices with reset functions have not yet been initialized. Hence, power-on does not guarantee output pin levels, I/O settings or contents of registers. A device is not initialized until the reset signal is received. A reset operation must be executed immediately after power-on for devices with reset functions.

⑤ POWER ON/OFF SEQUENCE

In the case of a device that uses different power supplies for the internal operation and external interface, as a rule, switch on the external power supply after switching on the internal power supply. When switching the power supply off, as a rule, switch off the external power supply and then the internal power supply. Use of the reverse power on/off sequences may result in the application of an overvoltage to the internal elements of the device, causing malfunction and degradation of internal elements due to the passage of an abnormal current.

The correct power on/off sequence must be judged separately for each device and according to related specifications governing the device.

⑥ INPUT OF SIGNAL DURING POWER OFF STATE

Do not input signals or an I/O pull-up power supply while the device is not powered. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Input of signals during the power off state must be judged separately for each device and according to related specifications governing the device.

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